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PWB mfg method e.g. for mounting semiconductor LSI - involves filling electrically conductive paste into through hole with squeegee

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Number of Countries: 001 Number of Patents: 001

Patent Family:

Patent No	Kind	Date	Applicat No	Kind	Date	Week
JP 8191184	A	19960723	JP 952719	A	19950111	199639 B

Priority Applications (No Type Date): JP 952719 A 19950111

Patent Details:

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JP 8191184	A		4	H05K-003/40	

Abstract (Basic): JP 8191184 A

The method involves covering a suction stage (1) with a sheet (2) that is permeable and elastic. A prepeg sheet (3) is formed above the covering sheet.

Multiple through holes (7) are drilled at predetermined intervals on prepeg sheet. An electrically conductive paste is filled into the holes formed on the prepeg sheet by a squeegee.

ADVANTAGE - Stabilises filling process of electrically conductive paste into holes. Improves maintenance nature and reliability of PCB.

Dwg.1/4

3/3,AB,LS/2 (Item 1 from file: 345)
DIALOG(R)File 345:Inpadoc/Fam.& Legal Stat
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Basic Patent (No,Kind,Date): JP 8191184 A2 960723

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MANUFACTURE OF PRINTED WIRING BOARD AND MANUFACTURING EQUIPMENT (English)

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Language of Document: Japanese

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DIALOG(R)File 347:JAPIO
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MANUFACTURE OF PRINTED WIRING BOARD AND MANUFACTURING EQUIPMENT

PUB. NO.: 08-191184 [JP 8191184 A]
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ABSTRACT

PURPOSE: To provide a method wherein high reliable filling of conducting paste for through holes is obtained and its manufacturing equipment.

CONSTITUTION: A sheet 2 having elasticity and ventilation is laid on a suction stage 1, and an object to be printed wherein through holes 7 are perforated in previously specified portions is set on the sheet 2. Conducting paste 5 supplied on the object to be printed is printed with a squeegee 6 while the object is sucked with the suction stage 1, and the through holes 7 are filled with the conducting paste 5.